

neurSoC A multiprocessor System-on-Chip with in-memory neural processing unit



COORDINATOR:
STMICROELECTRONICS



13 PARTNERS
9 COUNTRIES



01/09/2022 to
28/02/2026



€ 10.6M



CONTEXT

The **explosive growth of artificial intelligence** and its movement to the edge and end devices have prompted significant research on highly energy efficient and low-latency non-von Neumann computing paradigms such as In-Memory Computing (IMC). Those properties correspond to needs expressed for **industry** (predictive maintenance, robotics), **medical and healthcare**, **mobility** (autonomous driving, vehicle electrification, smart bikes-trains-airplanes), **urban management** (smart cities, IoT nodes), **consumer and personal electronics** (smartphones, watches, glasses, wearables, smart home) and **robotics** (drones, object detection and tracking).

CONSORTIUM



TECHNOLOGY

Despite the prominence of new memory technologies like SRAM and FLASH, **Phase Change Memory** remains a solid and reliable technology, able to achieve mass volume production and cost. NeuroSoC chosen approach is to use an **In-Memory Neural Processing Unit comprising IMC tiles based on ST's highly dense Phase-Change Memory** [1]. This IMNPU adopts the mixed-signal IMC paradigm that IBM recently validated in silicon [2]. Digital computational cores and memory will be integrated to allow for end-to-end inference of industry-relevant models.

TARGETED IMPACTS

The NeuroSoC architecture is expected to enhance the energy efficiency and compute density (TOPS/W/mm²) by **more than 100x** when compared to conventional general-purpose systems.

NeuroSoC will focus on a **scalable architecture** to target different needs for a variety of products.

In the end, NeuroSoC will deliver a **fully integrated solution with toolchain support** for development and optimization.

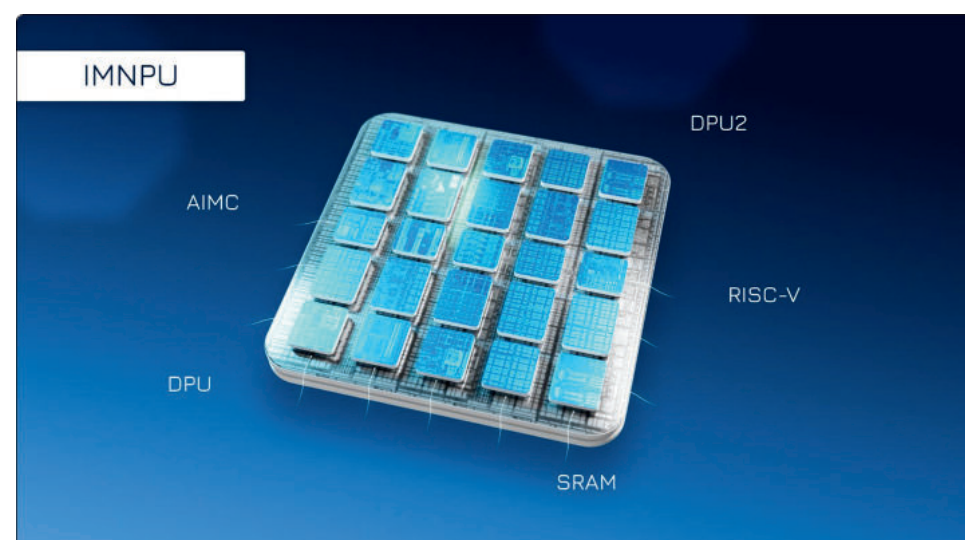
INNOVATION

NeuroSoC consortium is going for a **hybrid NPU approach**, using not only **IMC in PCM tiles** but **combining it with other technologies** (digital processing units, SRAM, RISC-V) to take advantage of the individual characteristics (compute precision, weight storage capabilities, flexibility etc.). The architecture of the IMNPU draws inspiration from research conducted within the IBM Research AI HW Center [2, 3].

The IMNPU will bring forward the following innovations:

- Architecture and design of IMNPU units,
- Tight integration with the processor,
- Software toolchain support,
- AI algorithms to fully exploit the architecture,
- Embedded cryptography.

IN-MEMORY NEURAL PROCESSING UNIT



REFERENCES

- [1] F. Arnaud et al., "High Density Embedded PCM Cell in 28nm FDSOI Technology for Automotive Micro-Controller Applications," IEDM 2020
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- [3] S. Jain et al., "A Heterogeneous and Programmable Compute-In-Memory Accelerator Architecture for Analog-AI Using Dense 2-D Mesh," TVLSI 2023

